

# BTM430/431 DATA MODULE

# Datasheet Version 5.4

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Bluetooth<sup>®</sup> AT Data Module Datasheet

# **REVISION HISTORY**

Revision	Date	Description	Approved By
1.0	3 Jan 2012	Initial Release	Jonathan Kaye
2.0	20 Mar 2012	Updates to firmware v11.28.1.0	Jonathan Kaye
3.0	11 May 2012	Formatting and general editing	Jonathan Kaye
4.0	7 Jan2013	Updated FCC Statement, new mech. drawings, general editing / formatting	Jonathan Kaye
4.1	15 Mar 2013	Converted to Laird formatting	Sue White
5.0	04 Feb 2014	Separated into two separate docs (Hardware Integration Guide and User Guide). Added a Related Documents section.	Sue White
5.1	06 Feb 2014	Updated the Bluetooth SIG Qualification section.	Jonathan Kaye
5.2	15 Aug 2014	Updated shipping tray image and added module package dimension image.	Jonathan Kaye
5.3	3 Sept 2014	Updated EU Declaration of Conformity	Jonathan Kaye
5.4	30 Nov 2016	Updated to Datasheet from Hardware Integration Guide	Sue White

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# **1 OVERVIEW AND KEY FEATURES**

The BTM430 and BTM431 Bluetooth<sup>®</sup> modules from Laird Technologies have been designed to meet the needs of developers who wish to add robust, short range Bluetooth data connectivity to their products. They are based on the market leading Cambridge Silicon Radio BC04 chipset, providing exceptionally low power consumption with outstanding range.

With physical sizes as small as 12.5 x 18.0mm and best of class, low-power operation, these modules are the ideal choice for applications where designers need both performance and minimum size. For maximum flexibility in systems integration, the modules are designed to support a separate power supply for I/O.

To aid product development and integration, Laird Technologies has integrated a complete Bluetooth protocol stack within the modules, including support for the Bluetooth Serial Port Profile. The modules are fully qualified as Bluetooth End Products, allowing designers to integrate them within their own products with no further Bluetooth Qualification. They can then list and promote their products on the Bluetooth website free of charge.

A comprehensive AT command interface is included, which simplifies firmware integration. Combined with a low cost developer's kit, this ensures that the choice of Laird Technologies Bluetooth modules guarantees the fastest route to market.

**RoHS** 

## 1.1 FEATURES AND BENEFITS 8

- Bluetooth<sup>®</sup> v2.0+EDR
- Adaptive Frequency Hopping to cope with interference from other wireless devices
- External or internal antenna options
- Comprehensive AT interface for simple programming
- Bluetooth<sup>®</sup> END Product Qualified
- Compact size
- Class 2 output 4dBm
- Low power operation
- UART interface
- PCM and SCO for external codec
- GPIO lines under AT control
- Support for multiple profiles
- Wi-Fi co-existence

### **1.2 APPLICATIONS**

- Embedded Devices
- Phone Accessories
- Security Devices
- Medical and Wellness Devices
- Automotive Applications
- Bluetooth Advertising
- ePOS

# **2 SPECIFICATIONS**

# 2.1 Detailed Specifications

Categories	Feature	Implementation	
Wireless Specification	Bluetooth®	Version 2.0+EDR	
	Transmit Class	Class 2	
	Frequency	2.402 – 2.480 GHz	
	Channels	79 channels Frequency Hopping Adaptive Frequency Hopping	
	Max Transmit Power	+4 dBm at antenna pad – BTM430 +4 dBm from integrated antenna – BTM431	
	Min Transmit Power	-27 dBm at antenna pad – BTM430 -27 dBm from integrated antenna – BTM431	
	Receive Sensitivity	-84dBm	
	Range	30m	
	Data Transfer Rate	Up to 300 kbps	
Antenna Modes	External Antenna	50 Ohm matched SMT pad – BTM430	
	Integrated Antenna (option)	+0dBi multilayer ceramic – BTM431	
UART Interface	Serial Interface	RS-232 bi-directional for commands and data 16550 compatible	
	Baud Rate	Configurable from 1,200 to 921,600bps Non-standard baud rates supported	
	Bits	8	
	Parity	Odd, even, none	
	Stop bits	1	
	Default Serial parameters	9600,n,8,1	
	Levels	Set by VDD_USB input	
	Modem Control	DTR, DSR, DCD, RI, RTS, CTS	
General Purpose Interface	I/O	8 general purpose I/O pins	
Audio	Support	1 PCM channel @ 64kbps	
	SCO Channels	Support SCO and eSCO	
	PCM Interface	Configurable as master or slave 8 bit A-law 8 bit µ-law 13 bit linear PCM Clock available when in slave mode	
Protocols and Firmware	Bluetooth Stack	V2.0 compliant. Fully integrated.	
	Profiles	GAP Generic Access Profile SDP Service Discovery Profile	
		SDF Service Discovery Frome	

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Categories	Feature	Implementation
		SPP Serial Port Profile
		DUN Dial Up Networking
		FTP Client
		OBEX Push client
		HSP Headset Profile
		HFP HandsFree Profile
	Firmware Upgrade	Available over UART
	Connection Modes	Point to point (cable replacement)
Command Interface	AT Instructions set Multipoint Capabilities	Comprehensive control of connection and module operation S Registers for non-volatile storage of parameters
Current Consumption	Data Transfer	Typically 32mA
	Low Power Sniff Mode	Less than 2.5mA
Supply Voltage	Supply	3.0V – 3.3V DC
	I/O	1.7V – 3.3V DC (independent of Supply)
	USB & UART	1.7V – 3.6V DC (independent of Supply)
Coexistence / Compatibility	WLAN (802.11)	2-wire and 3-wire hardware coexistence schemes supported
Connections	Interface	Surface Mount Pads
	External Antenna (BTM430)	Pad for 50 Ohm antenna
Physical	Dimensions	12.5mm x 18.0 x 3.4mm BTM430 12.5mm x 22.0mm x 3.4mm BTM431
	Weight	3 grams
Environmental	Operating Temperature	-30°C to +70°C
	Storage Temperature	-40°C to +85°C
Approvals	Bluetooth	Qualified as an END product
	FCC	Limited Modular Approval (BTM430) Full Modular Approval (BTM431)
	CE & R&TTE	Meets CE and R&TTE requirements
Miscellaneous	Lead free	Lead-free and RoHS compliant
	Warranty	1-Year Warranty
Development Tools	Development Kit	Development board and software tools DVK-BTM430 (Dev Kit with BTM430 module fitted) DVK-BTM431 (Dev Kit with BTM431 module fitted)

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# 2.2 **Pin Definitions**

Table 2: Pin Definitions

1         Unused           2         GND           3         UART_CTS         Clear to Send I/P         VUSB           4         UART_RXD         Receive data I/P         VUSB           5         UART_RTS         Request to Send O/P         VUSB           6         UART_TXD         Transmit data O/P         VUSB           7         GND             8         SPI_CSB         SPI bus chip select I/P         VIO           9         SPI_MISO         SPI bus serial O/P         VIO           10         SPI_MOSI         SPI bus serial VP         VIO           11         SPI_CLK         SPI bus clock I/P         VIO           12         VDD_USB         USB & UART supply voltage            13         VDD_IO         I/O supply voltage            14         VDD_IN         Main supply voltage            15         GND             16         PCM_IN         PCM data I/P         VIO           17         PCM_SYNC         PCM data O/P         VIO           18         PCM_CLK         PCM data O/P         VIO           19         PCM_OUT	Pin	Signal	Description	Voltage Specification
3UART_CTSClear to Send I/PVUSB4UART_RXDReceive data I/PVUSB5UART_RTSRequest to Send O/PVUSB6UART_TXDTransmit data O/PVUSB7GND8SPI_CSBSPI bus chip select I/PVIO9SPI_MISOSPI bus serial O/PVIO10SPI_MOSISPI bus serial I/PVIO11SPI_CLKSPI bus clock I/PVIO12VDD_USBUSB & UART supply voltage13VDD_IOI/O supply voltage14VDD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO20RESETModule reset I/PSee note 221GND23GND24UnusedSee note 327UnusedSee note 328GND (BTM430 only)Antenna connection (50 ohm matched)30GND (BTM430 only)Antenna connection (50 ohm matched)32UnusedSee note 333UnusedSee note 332UnusedSee note 3	1	Unused		
4UART_RXDReceive data I/PVUSB5UART_RTSRequest to Send O/PVUSB6UART_TXDTransmit data O/PVUSB7GND8SPI_CSBSPI bus chip select I/PVIO9SPI_MISOSPI bus serial O/PVIO10SPI_MOSISPI bus serial I/PVIO11SPI_CLKSPI bus chip select I/PVIO12VDD_USBUSB & UART supply voltage13VDD_IOI/O supply voltage14VDD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO23GNDSee note 324UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)Antenna connection (50 ohm matched)30GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	2	GND		
5UART_RTSRequest to Send O/PVUSB6UART_TXDTransmit data O/PVUSB7GND*********************************	3	UART_CTS	Clear to Send I/P	VUSB
6UART_TXDTransmit data O/PVUSB7GND8SPI_CSBSPI bus chip select I/PVIO9SPI_MISOSPI bus serial O/PVIO10SPI_MOSISPI bus serial I/PVIO11SPI_CLKSPI bus clock I/PVIO12VDD_USBUSB & UART supply voltage13VDD_IOI/O supply voltage14VDD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_OUTPCM lock I/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GNDSee note 3See note 324UnusedSee note 3See note 325UnusedSee note 3See note 326UnusedSee note 3See note 327UnusedSee note 3See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)30GND (BTM430 only)Antenna connection (50 ohm see note 331UnusedSee note 332UnusedSee note 3	4	UART_RXD	Receive data I/P	VUSB
7GND8SPI_CSBSPI bus chip select I/PVIO9SPI_MISOSPI bus serial O/PVIO10SPI_MOSISPI bus serial I/PVIO11SPI_CLKSPI bus clock I/PVIO12VDD_USBUSB & UART supply voltage13VDD_IOI/O supply voltage14VDD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO23GND24Unused24UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)Antenna connection (50 ohmSee note 329ANT (BTM430 only)Antenna connection (50 ohmSee note 331UnusedSee note 33132UnusedSee note 3	5	UART_RTS	Request to Send O/P	VUSB
8SPI_CSBSPI bus chip select I/PVIO9SPI_MISOSPI bus serial O/PVIO10SPI_MOSISPI bus serial I/PVIO11SPI_CLKSPI bus clock I/PVIO12VDD_USBUSB & UART supply voltage1313VDD_IOI/O supply voltage1414VDD_INMain supply voltage1515GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO2 / UART_DCDI/O for hostVIO23GND24Unused2524UnusedSee note 33227UnusedSee note 33228GND (BTM430 only)Antenna connection (50 ohm matched)30GND (BTM430 only)Antenna connection (50 ohm matched)32UnusedSee note 332UnusedSee note 332UnusedSee note 332UnusedSee note 3	6	UART_TXD	Transmit data O/P	VUSB
9SPI_MISOSPI bus serial O/PVIO10SPI_MOSISPI bus serial I/PVIO11SPI_CLKSPI bus clock I/PVIO12VDD_USBUSB & UART supply voltage13VDD_IOI/O supply voltage14VDD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GNDSee note 32624UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)Antenna connection (50 ohm matched)30GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	7	GND		
10SPI_MOSISPI bus serial I/PVIO11SPI_CLKSPI bus clock I/PVIO12VDD_USBUSB & UART supply voltage13VDD_IOI/O supply voltage14VDD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 327UnusedSee note 328GND (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	8	SPI_CSB	SPI bus chip select I/P	VIO
11SPL_CLKSPI bus clock I/PVIO12VDD_USBUSB & UART supply voltage13VDD_IOI/O supply voltage14VDD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)Antenna connection (50 ohm matched)30GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	9	SPI_MISO	SPI bus serial O/P	VIO
12VDD_USBUSB & UART supply voltage13VDD_IOI/O supply voltage14VDD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	10	SPI_MOSI	SPI bus serial I/P	VIO
13VDD_IOI/O supply voltage14VDD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GNDSee note 324UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (8TM430 only)Antenna connection (50 ohm matched)30GND (8TM430 only)See note 331UnusedSee note 332UnusedSee note 3	11	SPI_CLK	SPI bus clock I/P	VIO
14VD_INMain supply voltage15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	12	VDD_USB	USB & UART supply voltage	
15GND16PCM_INPCM data I/PVIO17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 329ANT (BTM430 only)Antenna connection (50 ohm see note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	13	VDD_IO	I/O supply voltage	
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17PCM_SYNCPCM sync I/PVIO18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	15	GND		
18PCM_CLKPCM clock I/PVIO19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused25UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	16	PCM_IN	PCM data I/P	VIO
19PCM_OUTPCM Data O/PVIO20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	17	PCM_SYNC	PCM sync I/P	VIO
20RESETModule reset I/PSee note 221GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	18	PCM_CLK	PCM clock I/P	VIO
21GPIO4BT_ACTIVE / BT_STATEVIO22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	19	PCM_OUT	PCM Data O/P	VIO
22GPIO2 / UART_DCDI/O for hostVIO23GND24Unused24UnusedSee note 325UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	20	RESET	Module reset I/P	See note 2
23GND24Unused25Unused26Unused27Unused28GND (BTM430 only)29ANT (BTM430 only)30GND (BTM430 only)30GND (BTM430 only)31Unused32Unused33Unused34See note 335See note 336See note 337Unused38See note 339ANT (BTM430 only)30See note 331Unused32Unused33See note 334See note 335See note 336See note 337See note 338See note 339See note 330See note 331Unused32See note 3	21	GPIO4	BT_ACTIVE / BT_STATE	VIO
24Unused25UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	22	GPIO2 / UART_DCD	I/O for host	VIO
25UnusedSee note 326UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	23	GND		
26UnusedSee note 327UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	24	Unused		
27UnusedSee note 328GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	25	Unused		See note 3
28GND (BTM430 only)See note 329ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	26	Unused		See note 3
29ANT (BTM430 only)Antenna connection (50 ohm matched)See note 330GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	27	Unused		See note 3
matched)30GND (BTM430 only)See note 331UnusedSee note 332UnusedSee note 3	28	GND (BTM430 only)		See note 3
31UnusedSee note 332UnusedSee note 3	29	ANT (BTM430 only)		See note 3
32 Unused See note 3	30	GND (BTM430 only)		See note 3
	31	Unused		See note 3
22 Upured Coo pote 2	32	Unused		See note 3
SS UNUSEU SEE NOLE S	33	Unused		See note 3
34 Unused See note 3	34	Unused		See note 3
35 Unused See note 3	35	Unused		
36 Unused See note 3				
37 Unused See note 3				
38 Unused	38	Unused		

Embedded Wireless Solutions Support Center: <u>http://ews-support.lairdtech.com</u>

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Pin	Signal	Description	Voltage Specification
39	Unused		
40	Unused		
41	GND		
42	GPIO1/ UART_RI	I/O for host	VIO
43	GPIO7	UART_DTR	VIO
44	GPIO8	UART_DSR	VIO
45	GND		
46	D-	Not used for AT module variants	VUSB
47	D+	Not used for AT module variants	VUSB
48	GPIO6	RF_ACTIVE	VIO
49	GPIO5	WLAN_ACTIVE	VIO
50	GPIO3	BT_PRIORITY	VIO

Note: 1. Unused pins may have internal connections and must not be connected.

Reset input is active low. Input is pulled up to VDD\_IN via 22k. Minimum reset pulse width is 5 ms.
 Pins 8 – 11 (SPI related) are only for Laird internal production purposes.

4. Pins 25-37 should be left not connected on modules with integrated antenna

### 2.3 **Operating Parameters**

#### Table 3: Operating Parameters

Recommended Operating Condit	ions	
OPERATING CONDITION	MIN	MAX
VDD_USB (USB compatibility not required)	1.7	3.6
VDD_USB (USB compatibility required)	3.1	3.6
VDD_IO	1.7	3.3
VDD_IN	3.0	3.3

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# 2.4 Voltage Specifications

Table 4: Voltage Specifications - VUSB

Logic Levels (VUSB)			
INPUT VOLTAGE LEVELS	MIN	TYP	MAX
V <sub>ih</sub>	0.7VDD_USB		
V <sub>il</sub> 2.7 <vdd_usb<3.0< td=""><td>-0.4</td><td></td><td>+0.8</td></vdd_usb<3.0<>	-0.4		+0.8
1.7 <vdd_usb<1.9< td=""><td>-0.4</td><td></td><td>+0.4</td></vdd_usb<1.9<>	-0.4		+0.4
OUTPUT VOLTAGE LEVELS	(1.7 < VDD_USB < 1.9)		
$V_{oh}$ (lout = -4mA)	VDD_USB – 0.4		
$V_{ol}$ (lout = 4mA)			0.4
OUTPUT VOLTAGE LEVELS	(2.7 < VDD_USB < 3.0)		
$V_{oh}$ (lout = -4mA)	VDD_USB – 0.2		
$V_{ol}$ (lout = 4mA)			0.2

Note: VDD\_USB must be connected to power the USB and UART interfaces.

Tahle 5	· Voltane	Specifications	- 1/10
I ADIC J	. vonaye	Specifications	- 10

3-1			
Logic Levels (VIO)			
INPUT VOLTAGE LEVELS	MIN	ТҮР	MAX
V <sub>ih</sub>	0.7VDD_IO		
V <sub>il</sub> 2.7 <vdd_io<3.0< td=""><td>-0.4</td><td></td><td>+0.8</td></vdd_io<3.0<>	-0.4		+0.8
1.7 <vdd_io<1.9< td=""><td>-0.4</td><td></td><td>+0.4</td></vdd_io<1.9<>	-0.4		+0.4
OUTPUT VOLTAGE LEVELS	(1.7 < VDD_USB < 1.9)		
$V_{oh}$ (lout = -4mA)	VDD_IO - 0.4		
$V_{ol}$ (lout = 4mA)			0.4
OUTPUT VOLTAGE LEVELS	(2.7 <vdd_usb<3.0)< td=""><td></td><td></td></vdd_usb<3.0)<>		
V <sub>oh</sub> (lout = -4mA)	VDD_IO - 0.2		
$V_{ol}$ (lout = 4mA)			0.2

# **3** APPLICATION NOTE FOR SURFACE MOUNT MODULES

### 3.1 Introduction

Laird Technologies surface mount modules are designed to conform to all major manufacturing guidelines. This application note is intended to provide additional guidance beyond the information that is presented in the User Manual. This Application Note is considered a living document and will be updated as new information is presented.

The modules are designed to meet the needs of a number of commercial and industrial applications. The modules are designed to be easily manufactured and conform to current automated manufacturing processes.

# 3.2 Shipping

Modules are shipped in ESD (Electrostatic Discharge) safe trays that can be loaded into most manufacturers pick and place machines. Layouts of the trays are provided in Figure 1 and Figure 2.

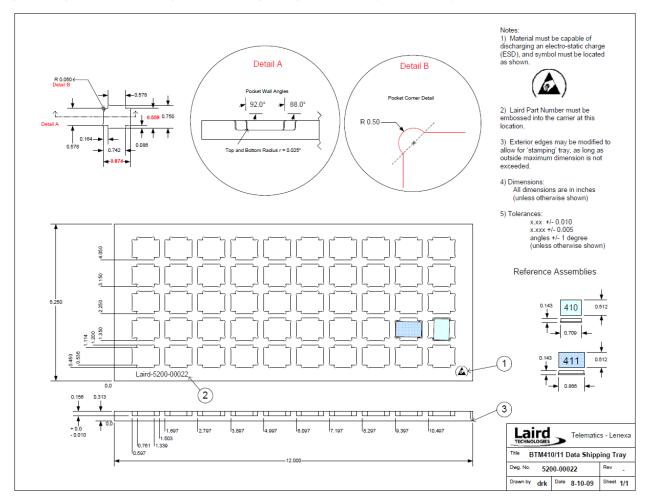


Figure 1: BTM430 and BTM431 Shipping Tray Details

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### **3.3 Reflow Parameters**

Laird Technologies surface mount modules are designed to be easily manufactured including reflow soldering to a PCB. Ultimately it is the responsibility of the customer to choose the appropriate solder paste and to ensure oven temperatures during reflow meet the requirements of the solder paste. Laird Technologies' surface mount modules conform to J-STD-020D1 standards for reflow temperatures.

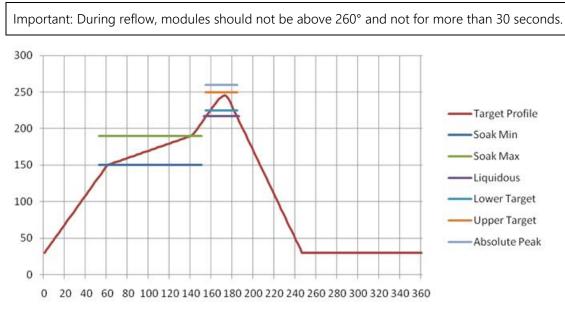


Figure 2: Recommended Reflow Temperature

Temperatures should not exceed the minimums or maximums presented in Table 6.

	Table 6: Recommended Maximum and minimum tempe	ratures
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Recommended Max & Min's		
SPECIFICATION	VALUE	UNIT
Temperature Inc./Dec. Rate (max)	3	°C / Sec
Temperature Decrease rate (goal)	2-3	°C / Sec
Soak Temp Increase rate (goal)	.5 - 1	°C / Sec
Flux Soak Period (Min)	60	Sec
Flux Soak Period (Max)	90	Sec
Flux Soak Temp (Min)	150	°C
Flux Soak Temp (max)	190	°C
Time Above Liquidous (max)	60	Sec
Time Above Liquidous (min)	20	Sec
Time In Target Reflow Range (goal)	30	Sec
Time At Absolute Peak (max)	30	Sec
Liquidous Temperature (SAC305)	217	°C
Lower Target Reflow Temperature	225	°C
Upper Target Reflow Temperature	250	°C
Absolute Peak Temperature	260	°C

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# **4 FCC REGULATORY STATEMENTS**

### 4.1 BTM430 FCC and Industry Canada Statements

The Final Equipment user manual must show the following statements:

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

To comply with the FCC RF exposure compliance requirements, this device and its antenna must not be co-located or operating to conjunction with any other antenna or transmitter.

Considerations for OEM integration:

This module has a limited modular approval. Approval with any other antenna configuration or layout other than that approved will necessitate additional radiated emission testing to be performed.

To inherit the modular approval, the antennas for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons and must not be co-located or operating in conjunction with any other antenna or transmitter.

This module was approved with the following antenna:

RF Solutions: ANT-24G-WHJ-SMA 0dBi

Operation of this module with any other antenna will require additional testing to be performed.

Co-location with other radio transmitting devices operating concurrently in the same band will require additional testing and certification.

Designers should note the distinction that the FCC makes regarding portable and mobile devices. Mobile devices are defined as products that are not used closer than 20cm to the human body, whereas portable devices can be used closer that 20cm to the body. A device may be used in portable exposure conditions with no restrictions on host platforms when the averaged output power is less than the low power threshold for an uncontrolled environment  $\leq 60/f$  (GHz) i.e. 25 mW for a 2.4 GHz device. The maximum Power Exposure for the BTM430 has been evaluated and found to comply with the low power threshold for an uncontrolled environment.

Refer to FCC document KDB 447498 for more information on RF exposure procedures and equipment authorization policies for mobile and portable devices.

FCC Labeling requirement

If the FCC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following: "Contains Transmitter Module FCC ID: PI4410B" or "Contains FCC ID: PI4410B." Any similar wording that expresses the same meaning may be used.

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### 4.2 BTM431 FCC and Industry Canada Statements

The user manual must show the following statements:

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

To comply with the FCC RF exposure compliance requirements, this device and its antenna must not be co-located or operating to conjunction with any other antenna or transmitter.

Considerations for OEM integration:

To inherit the modular approval, the antennas for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons and must not be co-located or operating in conjunction with any other antenna or transmitter.

Co-location with other radio transmitting devices operating concurrently in the same band will require additional testing and certification.

Designers should note the distinction that the FCC makes regarding portable and mobile devices. Mobile devices are defined as products that are not used closer than 20cm to the human body, whereas portable devices can be used closer that 20cm to the body. A device may be used in portable exposure conditions with no restrictions on host platforms when the averaged output power is less than the low power threshold for an uncontrolled environment  $\leq$  60/f (GHz) i.e. 25 mW for a 2.4 GHz device. The Maximum Power Exposure for the BTM431 has been evaluated and found to comply with the low power threshold for an uncontrolled environment.

Refer to FCC document KDB 447498 for more information on RF exposure procedures and equipment authorization policies for mobile and portable devices.

#### FCC Labelling requirement

If the FCC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following: "Contains Transmitter Module FCC ID: PI4411B" or "Contains FCC ID: PI4411B." Any similar wording that expresses the same meaning may be used.

# 5 EU DECLARATION OF CONFORMITY – BTM430 / BTM431

Manufacturer:	Laird
Product:	BTM410 / BTM411 / BTM420 / BTM421 / BTM430 / BTM431 / BTM441 / BTM443 / BTM461
EU Directive:	RTTE 1995/5/EC
Conformity Assessment:	Annex IV

### **1.1** Reference Standards used for Presumption of Conformity

Article Number	Requirement	Reference standard(s)
3.1a	Health and Safety	EN 60950-1:2005 (2 <sup>nd</sup> Ed); +Am1:2009 +Am2:2013 EN 60950-1:2006+A11+a1:2010+A12:2011+A2:2013
3.1a	RF Exposure	EN 62479:2010
3.1b	Protection requirements with respect to electromagnetic compatibility	EN 301 489-1 V1.9.2 (2011-09) EN 301 489-17 V2.2.1 (2012-09) Emissions: EN55022:2010 /AC:2011 (ClassB) Immunity: EN61000-4-2:2009 EN61000-4-3:2006 /A1:2008 /A2:2010
3.2	Means of the efficient use of the radio frequency spectrum	EN 300 328 V1.8.1 (2012-06)

## **1.2 Declaration:**

We, Laird, declare under our sole responsibility that the essential radio test suites have been carried out and that the above product to which this declaration relates is in conformity with all the applicable essential requirements of Article 3 of the EU Directive 1995/5/EC, when used for its intended purpose.

Place of Issue:	Laird 11160 Thompson Ave. Lenexa, KS 66219
Date of Issue:	October 2009
Name of Authorized Person:	Daniel Waters / Certifications Specialist

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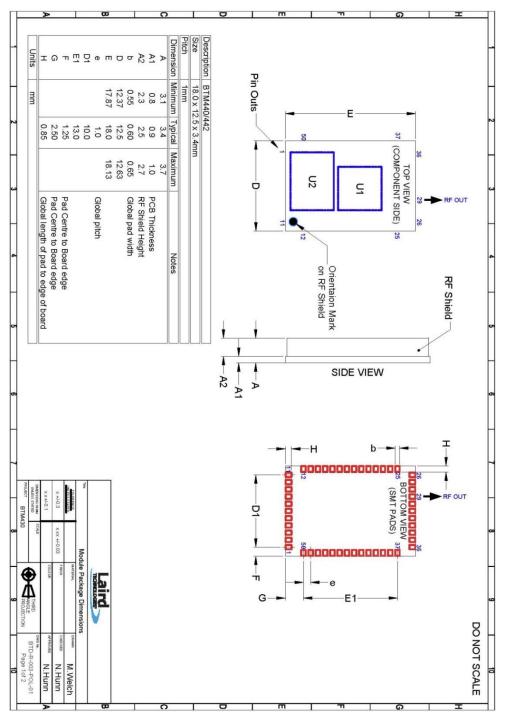
Signature:

Danie/ E (Sators

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# **6** MECHANICAL DETAILS

# 6.1 BTM430 Mechanical Details



Module Keep-Out Area: An area of 1.5mm around the module should be reserved as a keep-out area. No other components should be placed in this area.

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## module. 2: Ensure no exposed copper under module to avoid shorting to test points on underside of Notes 1 Connect External Antenna to RF I/O pin 29 with 50ohm microstrip or coplaner waveguide and/or process capability. 3: The user may modify the PCB land pattern dimensions based on their experience PCB LAND PATTERN/DECAL DIMENSIONS MODULE OUTLINE (See note 2) 13.70 pin pitch 1.00 x 10-1.85 0000000000 (ecommended Land Pattern/Decal 6 -3.10 pin pitch -1.00 x 13--19.20- Pad Length 1.65 Typ RF OUT (See Note 1) Pad Width 0.70 Typ **BTM43** THRD PROJE Laind TIOP DO NOT SCALE BTD-R-003-POL-01 Page 2 of 2 Page M.Welch N.Hunn N.Hunn

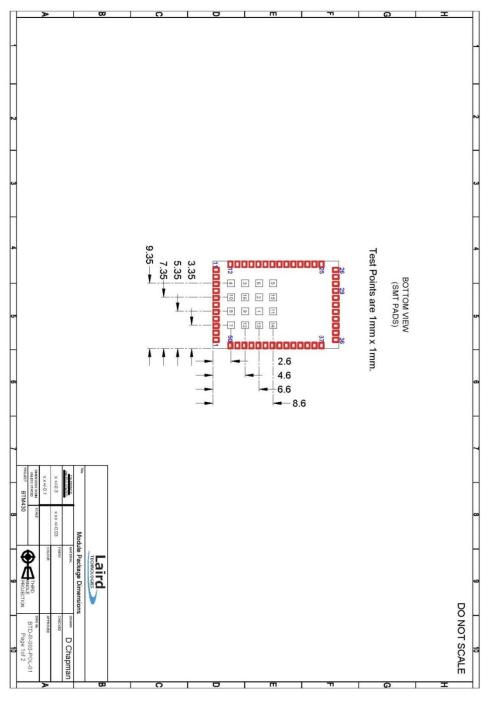
# 6.2 BTM430 Mechanical Details

Module Keep-Out Area: An area of 1.5mm around the module should be reserved as a keep-out area. No other components should be placed in this area.

The Development Kit Schematics for this product can be accessed from the following link: <u>Development Kit Schematics – BTM430 / BTM431</u>

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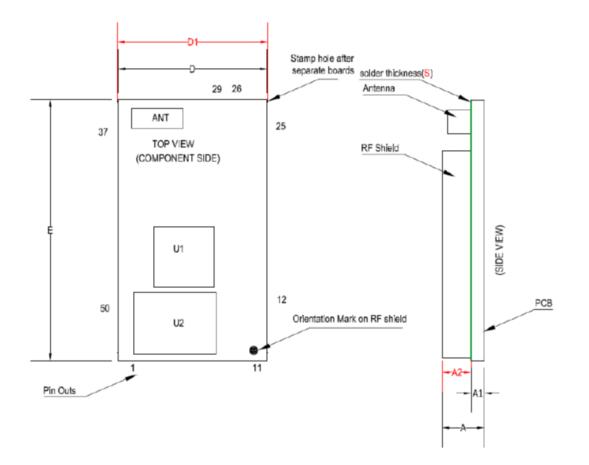




WARNING: Test point dimensions are for reference only. *DO NOT* make electrical connections to these test points, this will void the warranty. Laird does not recommend routing on the top layer underneath the module.

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### 6.4 BTM431 Mechanical Details

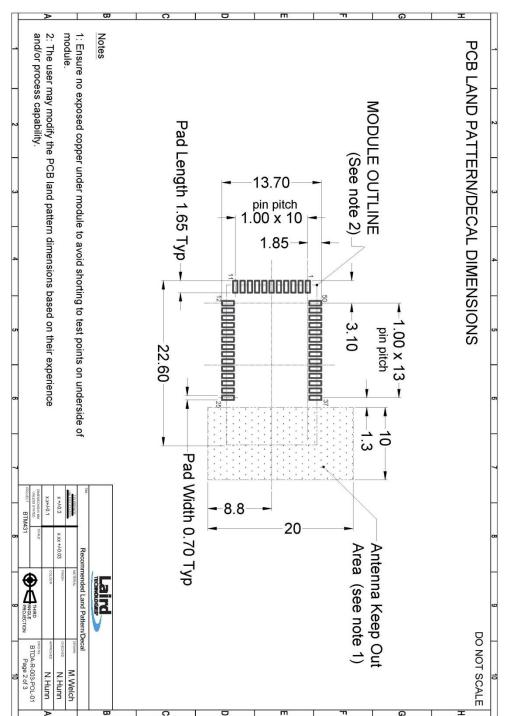


Description	BTM4X1			
Size	22.0x12.5x3.0495mm			
Pitch	1mm			
Dimension	Minimum	Typical	Maximum	Notes
А	2.822mm	3.0495mm	3.277mm	1)A is consist of A1 and A2
A1	0.8mm	0.9mm	1.0mm 2)A2 include solder and shield	
A2	2.022mm	2.1495mm	2.277mm	3)D1 measured on stamp hole location after
D	12.37mm	12.5mm	12.63mm	- depanelization
D1	12.37mm	12.5mm	13.03mm	-
E	21.87mm	22.0mm	22.13mm	

Module Keep-Out Area: An area of 1.5mm around the module should be reserved as a keep-out area. No other components should be placed in this area.

The Development Kit Schematics for this product can be accessed from the following link: <u>Development Kit Schematics – BTM430 / BTM431</u>

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# 6.5 BTM431 Mechanical Details

Module Keep-Out Area: An area of 1.5mm around the module should be reserved as a keep-out area. No other components should be placed in this area.

The Development Kit Schematics for this product can be accessed from the following link: <u>Development Kit Schematics – BTM430 / BTM431</u>

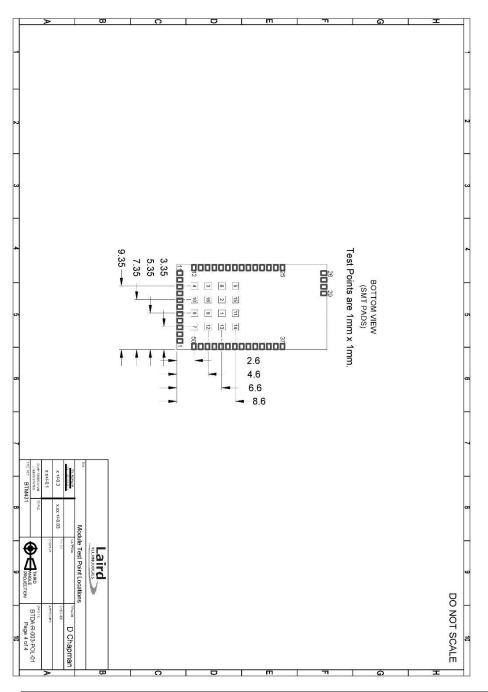
## 6.6 BTM431 Mechanical Details

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N 	<ul> <li>4.) Ensure no exposed copper under module on host p.c. board to avoid shorting to test points on underside of module.</li> <li>5.) The user may modify the PCB land pattern dimensions based on their experience and/or process capability.</li> </ul>	edge of the host p.c. board and preferably in the corner with the antenna facing the corner. 3.) Antenna keep out area definition comes from the module's Developer Kit board which was used for module development and antenna performance evaluation.	<ol> <li>Ensure their is no copper in the antenna keep out area on any layers of the host p.c. board. Also keep all mounting hardware or any metal clear of this area to prevent affecting proper antenna radiation.</li> <li>For best antenna performance the module should be placed on the</li> </ol>	
The         Application Notes           101 EBDIG         Mortesu           101 EBDIG         EBDIG           101 EBDIG         EBDIG	c. board to avoid ns based on their	with the antenna dule's Developer antenna	ea on any layers of any metal clear of placed on the	~
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### 6.7 BTM431 Mechanical Details



WARNING: Test point dimensions are for reference only. *DO NOT* make electrical connections to these test points, this will void the warranty. Laird does not recommend routing on the top layer underneath the module.

# **7** ORDERING INFORMATION

Part Number	Description
BTM430	Bluetooth AT Data Module (external antenna)
BTM431	Bluetooth AT Data Module (with integrated antenna)
DVK – BTM430	Development board with BTM430 module soldered in place
DVK – BTM431	Development board with BTM431 module soldered in place

## 7.1 General Comments

This is a preliminary datasheet. Please check with Laird Technologies for the latest information before commencing a design. If in doubt, ask.

Refer to the schematic BTDMD-R-001.pdf for the Development Kit on the following two pages for examples of typical pin connections. A pdf of the schematic can be downloaded from the product web page.

# 8 BLUETOOTH SIG QUALIFICATION

The BTM430 and BTM431 modules are listed on the Bluetooth SIG website as qualified End Products.

Design Name	Owner	Declaration ID	Link to listing on the SIG website
BTM430, BTM431	Laird Technologie s	B016510	https://www.bluetooth.org/tpg/QLI viewQDL.cfm?qid=16510

It is a mandatory requirement of the Bluetooth Special Interest Group (SIG) that every product implementing Bluetooth technology has a Declaration ID. Every Bluetooth design is required to go through the qualification process, even when referencing a Bluetooth Design that already has its own Declaration ID. The Qualification Process requires each company to registered as a member of the Bluetooth SIG – www.bluetooth.org

The following link provides a link to the Bluetooth Registration page: <u>https://www.bluetooth.org/login/register/</u>

For each Bluetooth Design it is necessary to purchase a Declaration ID. This can be done before starting the new qualification, either through invoicing or credit card payment. The fees for the Declaration ID will depend on your membership status, please refer to the following webpage: <a href="https://www.bluetooth.org/en-us/test-qualification/qualification-overview/fees">https://www.bluetooth.org/en-us/test-qualification/qualification-overview/fees</a>

For a detailed procedure of how to obtain a new Declaration ID for your design, please refer to the following SIG document:

https://www.bluetooth.org/DocMan/handlers/DownloadDoc.ashx?doc\_id=283698&vId=317486

To start the listing, go to: https://www.bluetooth.org/tpg/QLI SDoc.cfm

In step 1, select the option, Reference a Qualified Design and enter 16510 in the End Product table entry. You can then select your pre-paid Declaration ID from the drop down menu or go to the Purchase Declaration ID page, (please note that unless the Declaration ID is pre-paid or purchased with a credit card, it will not be possible to proceed until the SIG invoice is paid.

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Once all the relevant sections of step 1 are complete, complete steps 2, 3 and 4 as described in the help document. Your new Design will be listed on the SIG website and you can print your Certificate and DoC.

For further information please refer to the following training material; <u>https://www.bluetooth.org/en-us/test-gualification/gualification-overview/listing-process-updates</u>

### 8.1 Additional Assistance

Please contact your local sales representative or our support team for further assistance:

Laird Technologies Connectivity Products Business Unit

Support Centre: <u>http://ews-support.lairdtech.com</u>

Email: wireless.support@lairdtech.com

Phone: Americas: +1-800-492-2320 Option 2

Europe: +44-1628-858-940

Hong Kong: +852 2923 0610

Web: <u>http://www.lairdtech.com/bluetooth</u>

# **9 RELATED DOCUMENTS**

The following additional BTM430/431 technical documents are also available from the <u>Laird BTM430/431</u> product page under the Documentation tab:

- Product Brief
- User Guide
- Firmware Release Notes Version 11.28.1.0
- Development Kit Schematics



# Innovative **Technology** for a **Connected** World

Laird Technologies is the world leader in the design and manufacture of customized, performance-critical products for wireless and other advanced electronics applications. Laird Technologies partners with its customers to find solutions for applications in various industries such as:

- Network Equipment
- Telecommunications
- Data Communications
- Automotive Electronics
- Computers
- Aerospace
- Military
- Medical Equipment
- Consumer Electronics

Laird Technologies offers its customers unique product solutions, dedication to research and development, as well as a seamless network of manufacturing and customer support facilities across the globe.

#### CONN-HIG-BTM430-431

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